

# A numerical approach to fabricate defect free and structurally sound components by additive manufacturing

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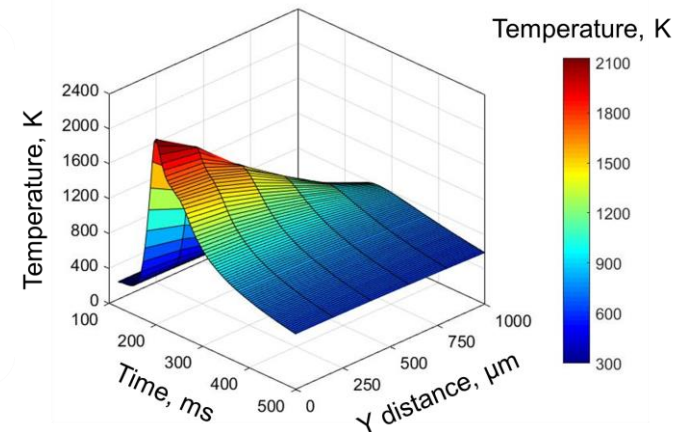
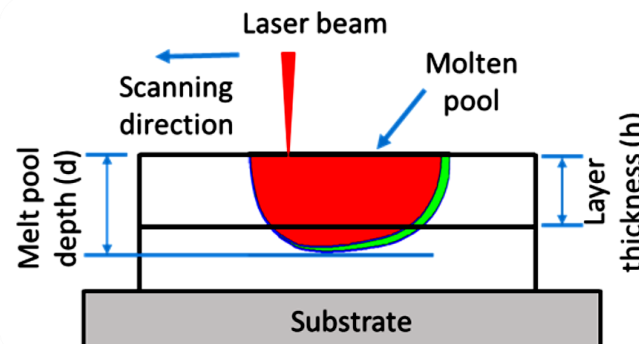
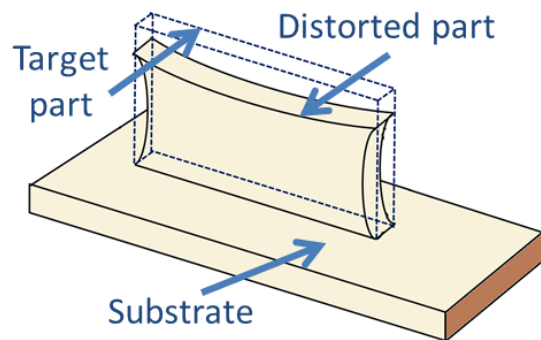
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Influence of transport phenomena on structure, property and defect

Heat transfer and fluid flow model to capture the real time physics

Dimensional analysis and back of the envelope calculations



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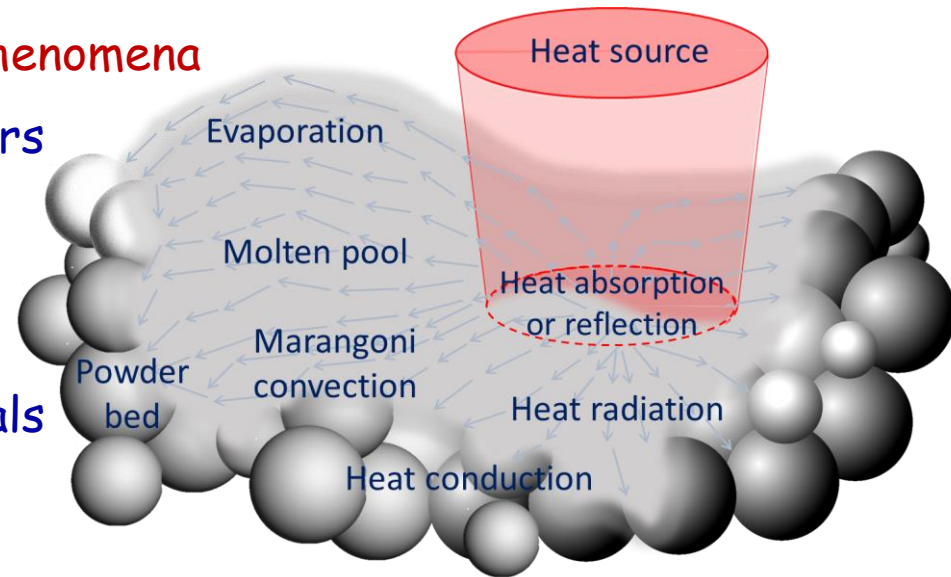
Understanding the role of transport phenomena

=> Cooling rate, solidification parameters

=> Distortion, lack of fusion

Selection of proper process conditions

=> Reduces expensive experimental trials



**Approach:**

3D transient heat transfer and fluid flow model

=> Calculates important metallurgical variables

Dimensional analysis and back of the envelope calculations

=> Better understanding of process-structure-property relationship

DebRoy et al. 2018  
Progress in Materials Science.

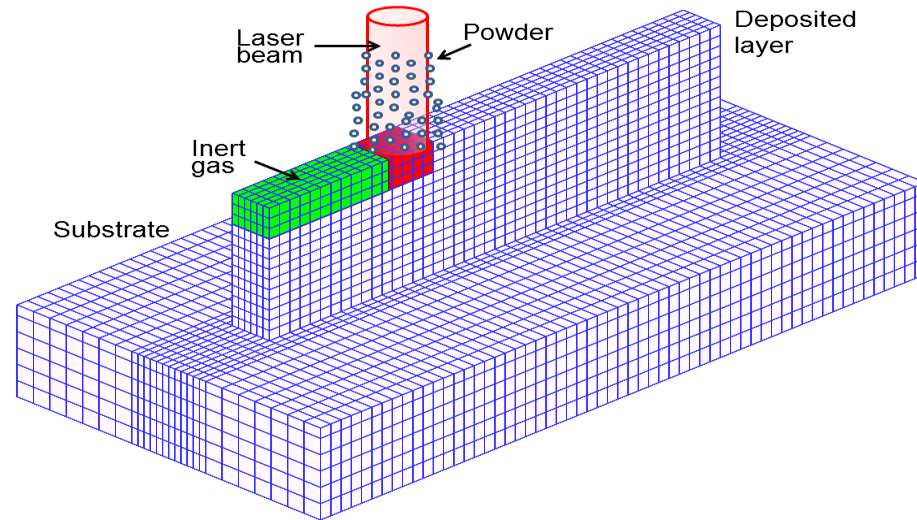
# Heat transfer and fluid flow model



Solve equations of conservation of mass, momentum and energy

## INPUT

Process parameters  
Material properties



## OUTPUT

Transient  
temperature &  
velocity fields,  
solidification  
parameters ...

Calculation domain: about **250,000 cells**

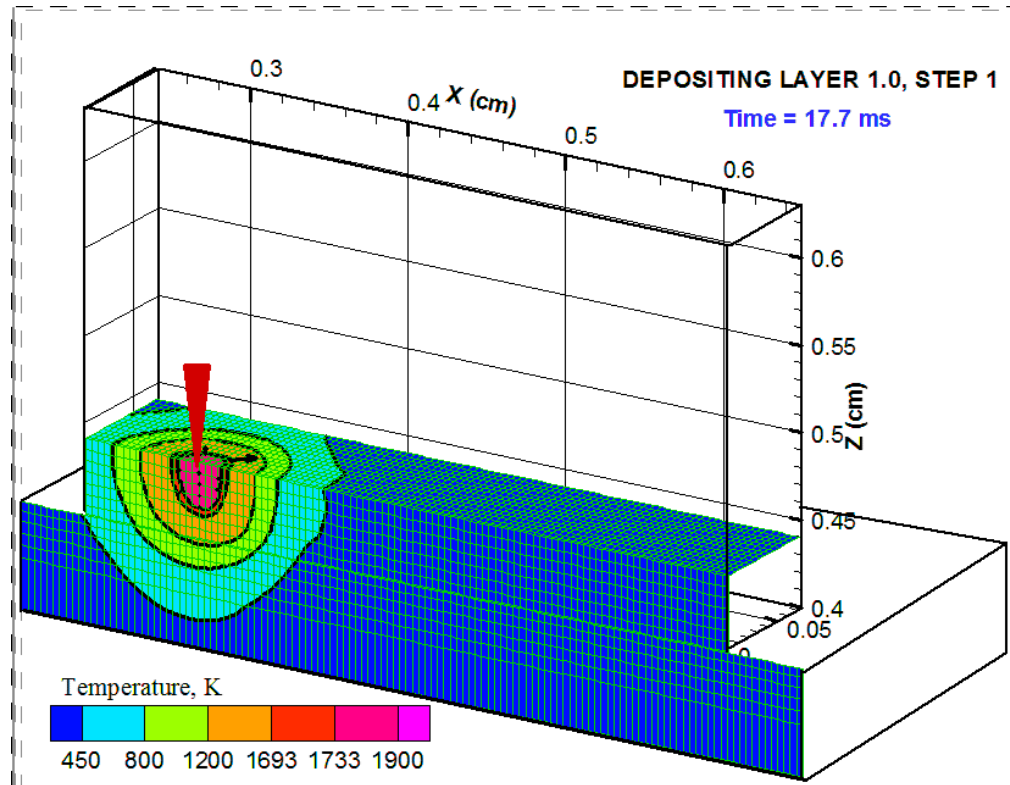
**Five main variables:** three components of velocities, pressure & enthalpy

**1.25 million algebraic equations** ( $250000 \times 5$ )

100 iteration at any time step => **0.125 billion equations/time step**

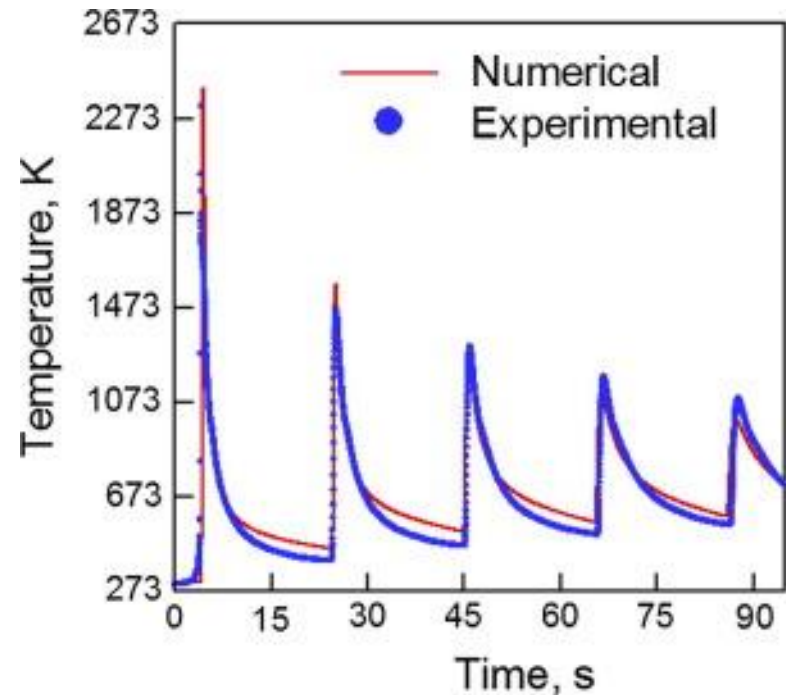
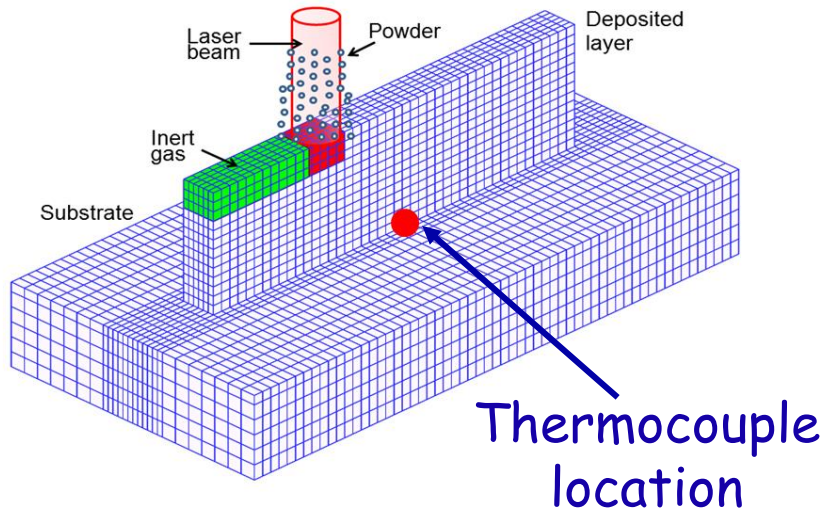
1000 time step => **125 billion total equations**

# 3D transient temperature distribution



Material	Laser power (W)	Beam radius (mm)	Scanning speed (mm/s)	Layer thickness (mm)	Substrate thickness (mm)
SS 316	210	0.5	12.5	0.38	4

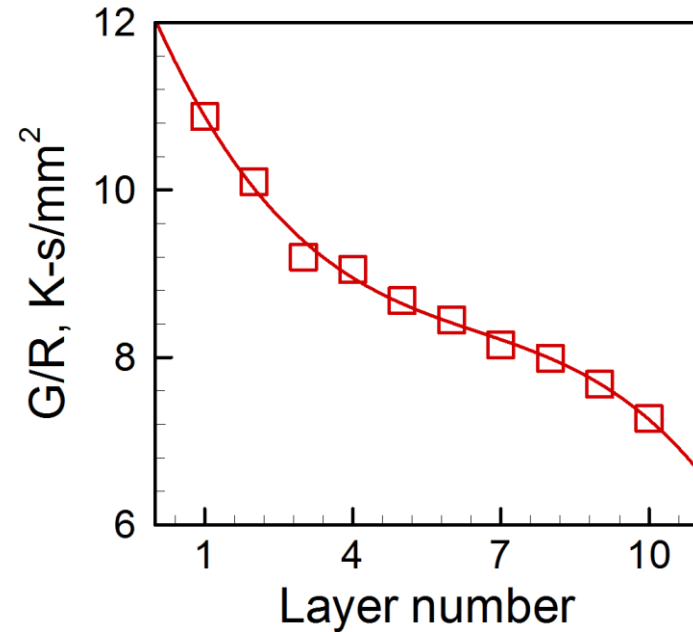
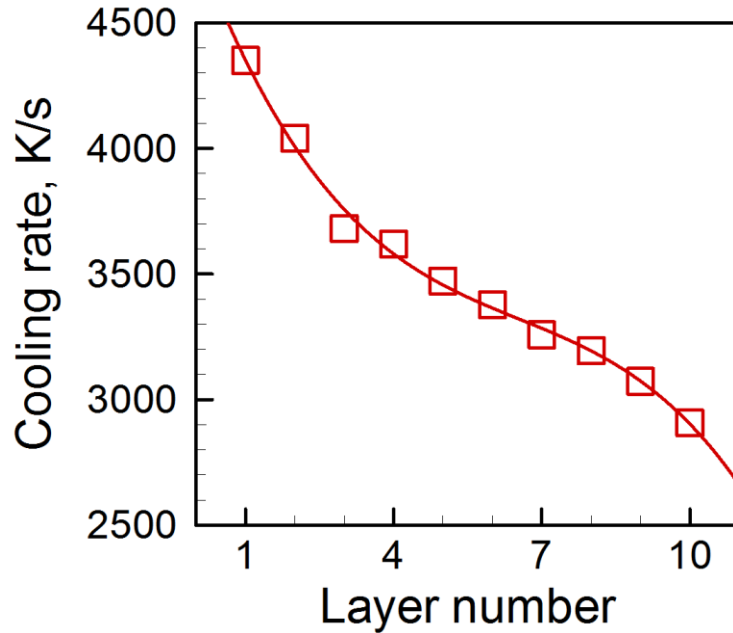
# Experimental validation: Thermal cycle



Liquidus temperature = 1878 K

Material	Laser power (W)	Beam radius (mm)	Scanning speed (mm/s)	Layer thickness (mm)	Substrate thickness (mm)
Ti-6Al-4V	2000	1.5	10.6	0.9	10

# Cooling rates and solidification parameters



- => Temperature gradient =>  $G$   
Solidification growth rate =>  $R$
- => Cooling rates are calculated during solidification
- => Calculations are done at mid-length of the deposit just below the laser beam
- => For the higher layers, heat transfer through the substrate decreases that reduce the cooling rate

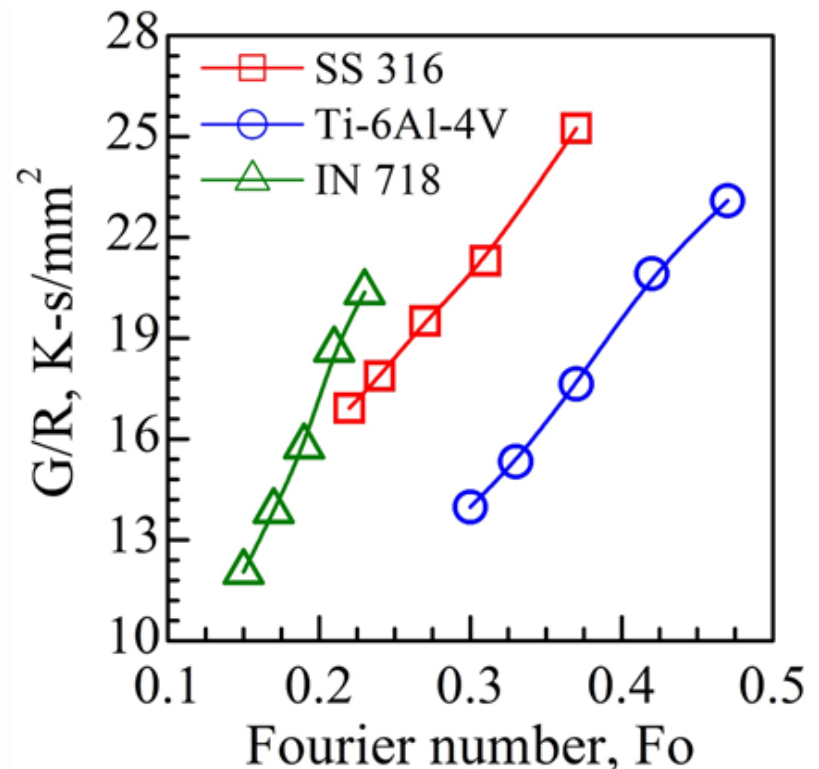
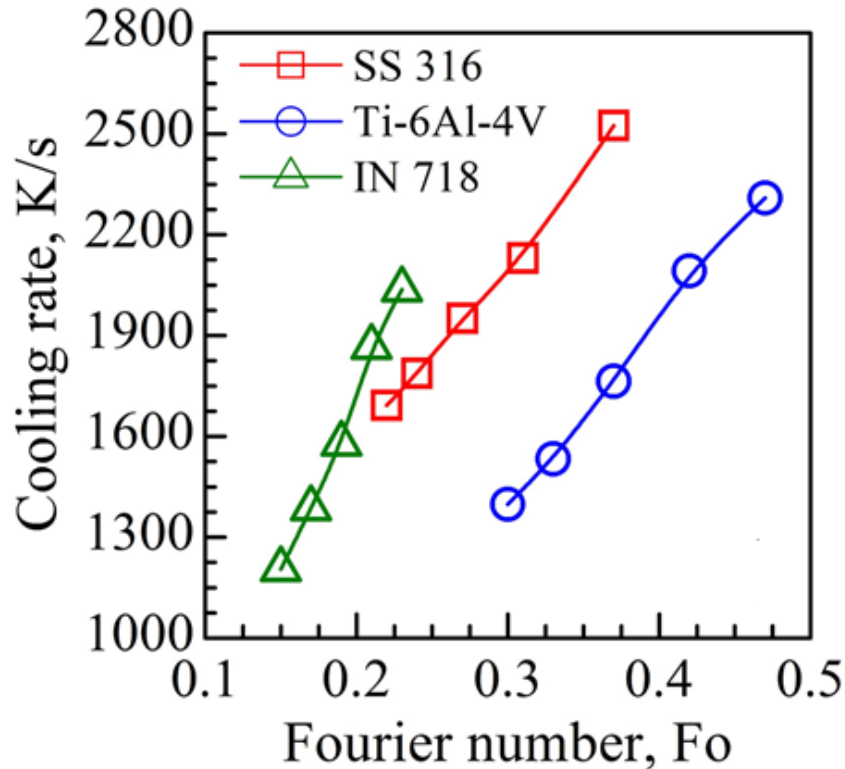
Alloy	IN 718
Laser power (W)	600
Beam radius (mm)	0.5
Scanning speed (mm/s)	20
Layer thickness (mm)	0.38
Substrate thickness (mm)	4

# Effects of heat dissipation and storage



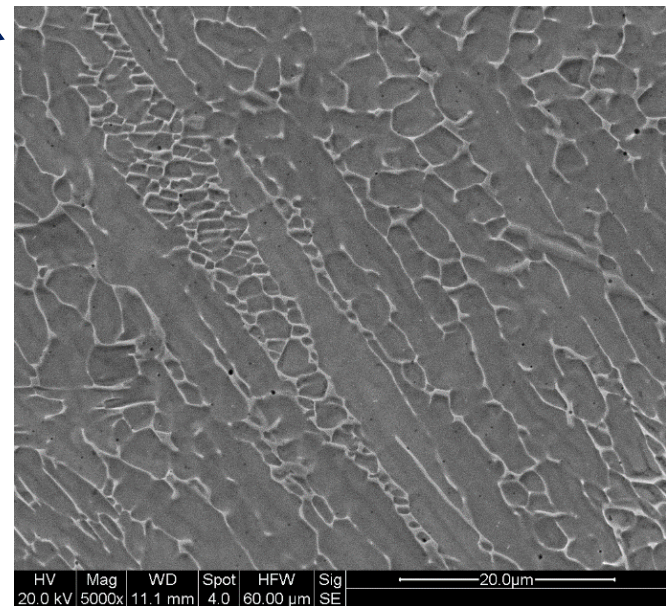
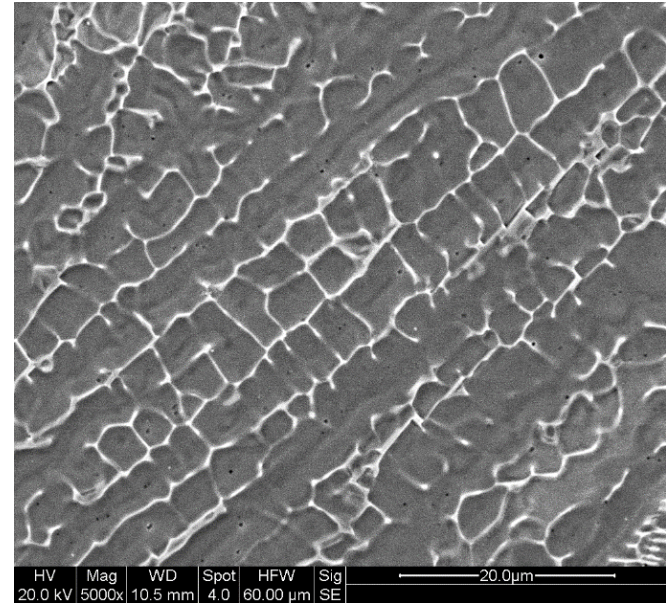
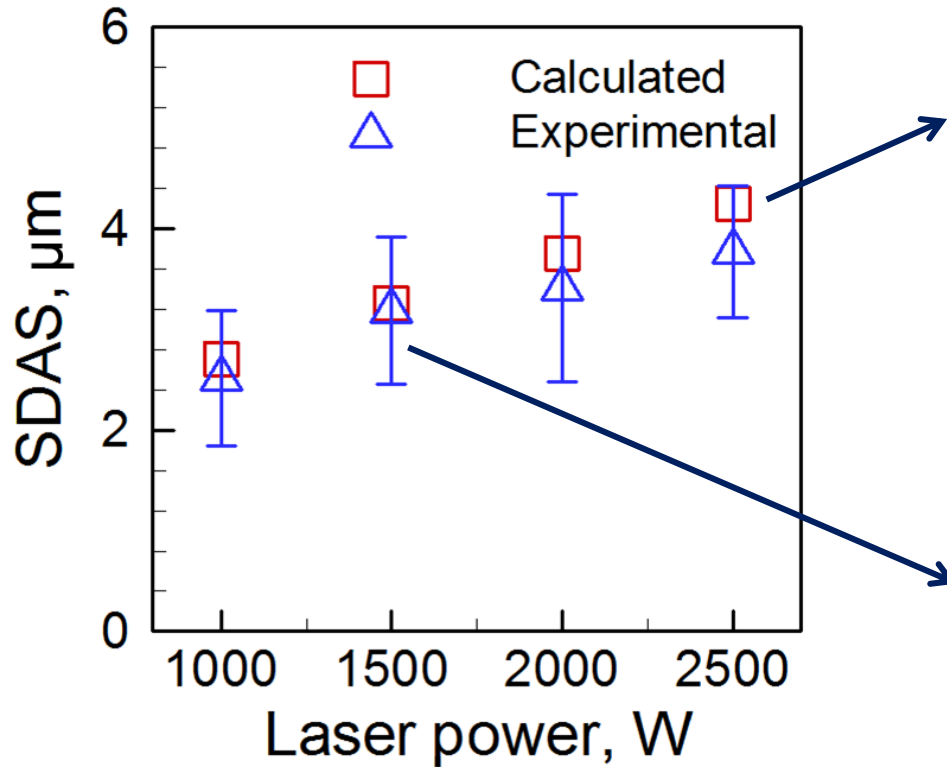
Temperature gradient  $\Rightarrow G$

Solidification growth rate  $\Rightarrow R$



$$\text{Fourier number } (F_0) = \frac{\text{Heat dissipation rate}}{\text{Heat storage rate}}$$

# Secondary dendritic arm spacing (SDAS) for SS 316



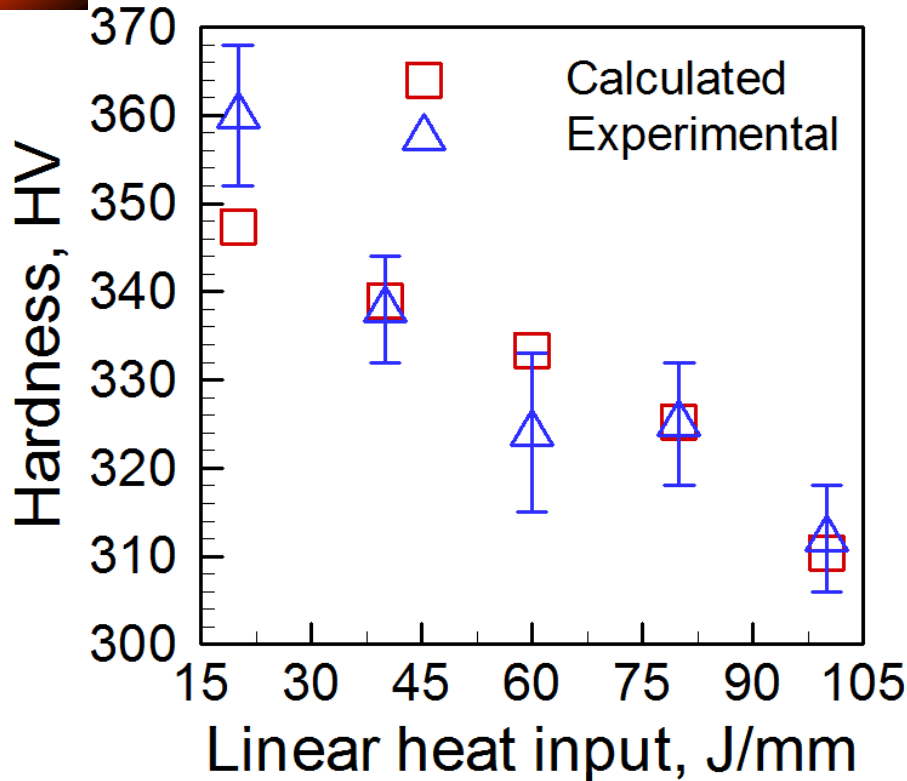
$$\lambda = 50(GR)^{-0.4}$$

$\lambda$  = Secondary dendritic arm spacing,  $\mu\text{m}$

$GR$  = Cooling rate, K/s



# Hardness of SS 316



$$\text{Linear heat input} = \frac{\text{Laser power}}{\text{Scanning speed}}$$

$$\sigma_y = \sigma_0 + K_y (\lambda)^{-0.5}$$

$\sigma_y$  = Yield strength, MPa

$\sigma_0 = 240 \text{ MPa}$ ,  $K_y = 279 \text{ MPa } (\mu\text{m})^{0.5}$

$\lambda$  = Secondary dendritic arm spacing,  $\mu\text{m}$

$$H_v = 3 \sigma_y (0.1)^{-0.25}$$

$H_v$  = Vicker's hardness

More heat deposited per unit length  $\Rightarrow$  Slow cooling  $\Rightarrow$  Large SDAS  $\Rightarrow$  Low hardness (SS 316)

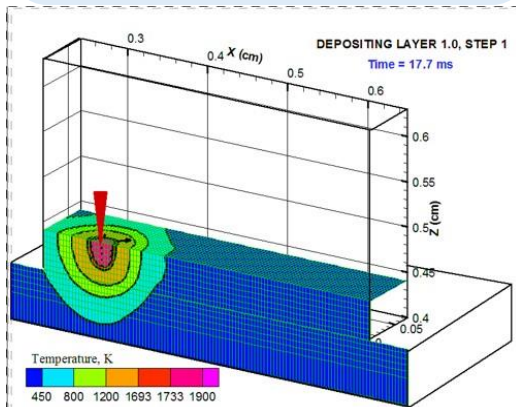
Experimental data are taken from Zhang et al. Mater. Des. 2014.

# Calculation of distortion and residual stresses



3D Transient heat transfer and fluid flow model

Temperature and velocity distribution for the domain

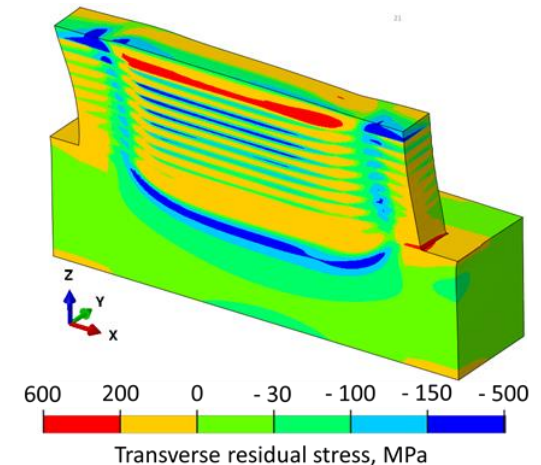


Thermal strain, stress, deformation for the domain

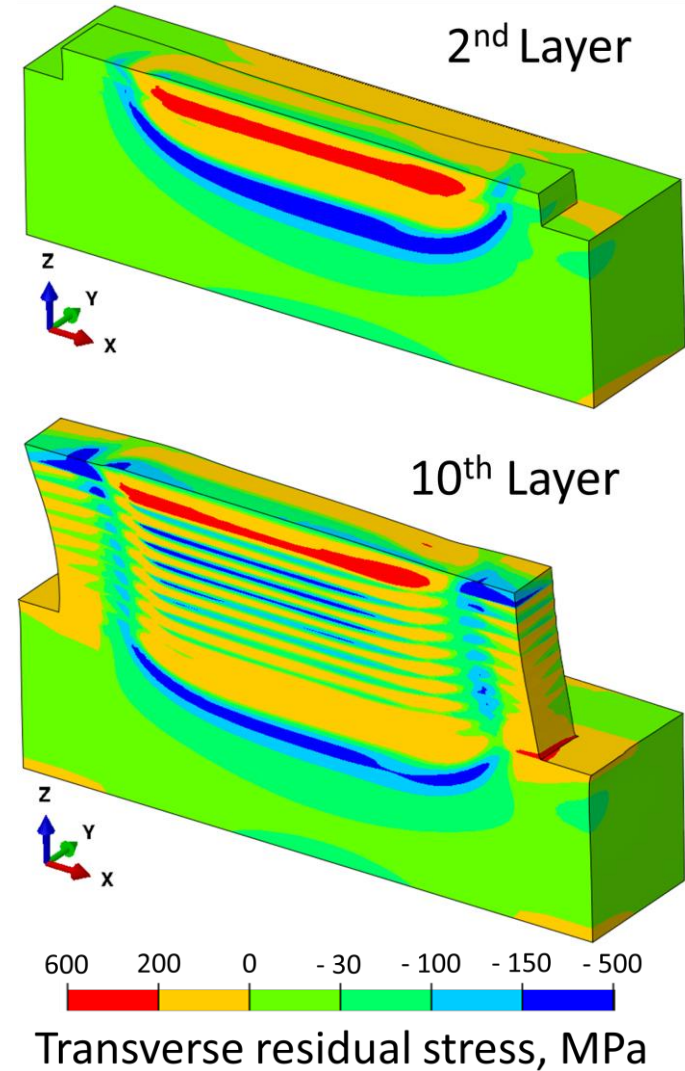
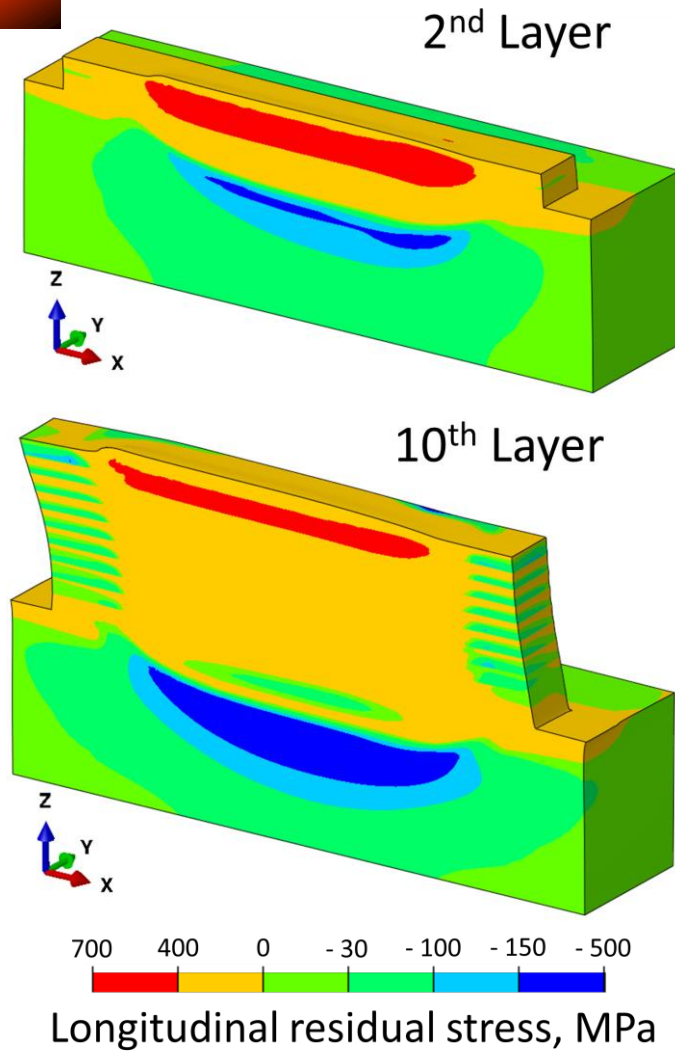
Abaqus output database (.odb) file

Using a Python script

Geometry, mesh and temperature field



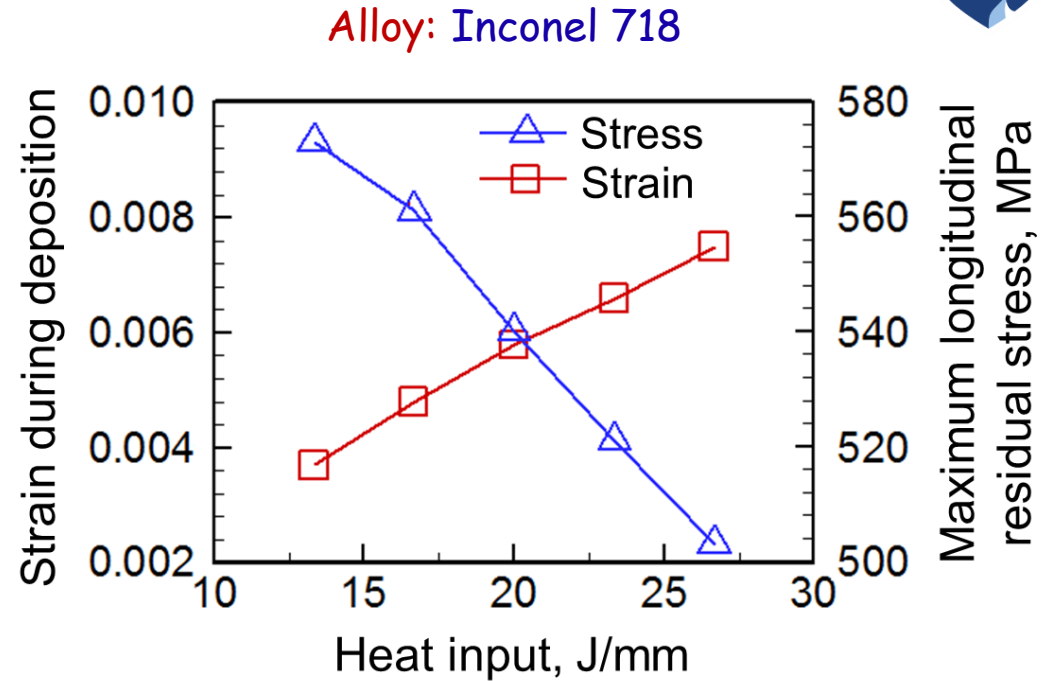
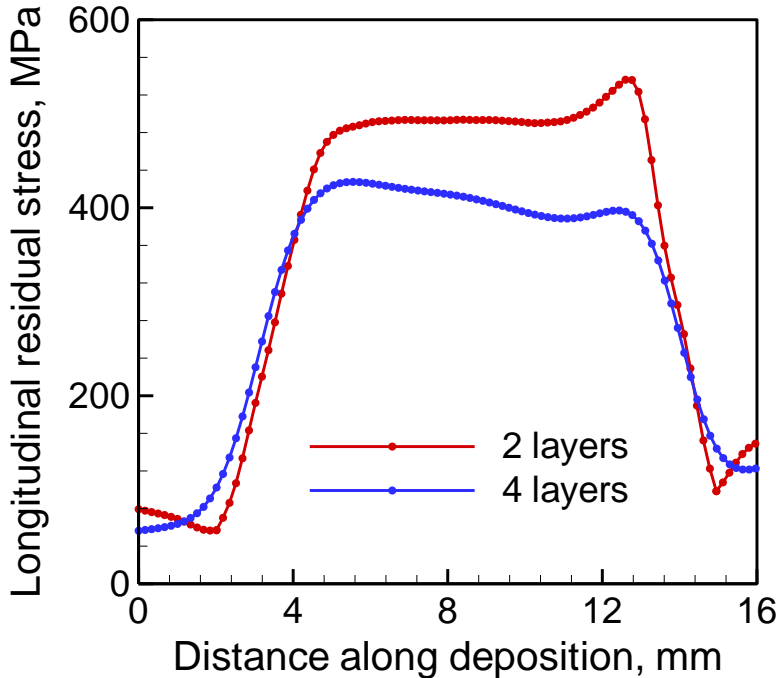
# Calculated residual stresses



Alloy: Inconel 718,  
Laser power: 300 W, Speed: 15 mm/s

Scanning direction is along the positive x-axis  
10 x magnification

# Effects of layer thickness and heat input



- => Residual stresses can be decreased as much as 30% by doubling the number of layers to build the same height.
- => Doubling the heat input reduces the residual stresses by about 20% and enhances the distortion by about 2.5 times.
- => An appropriate heat input should be selected by trading off both distortion and residual stresses.

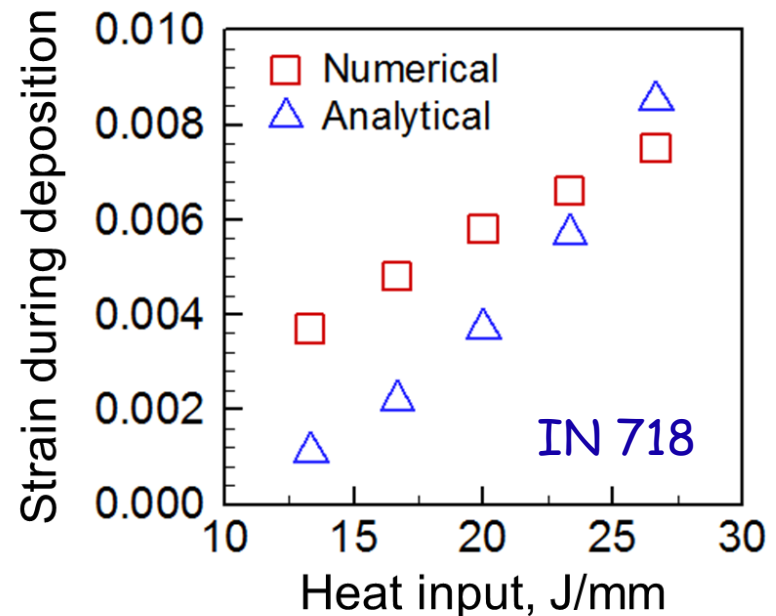
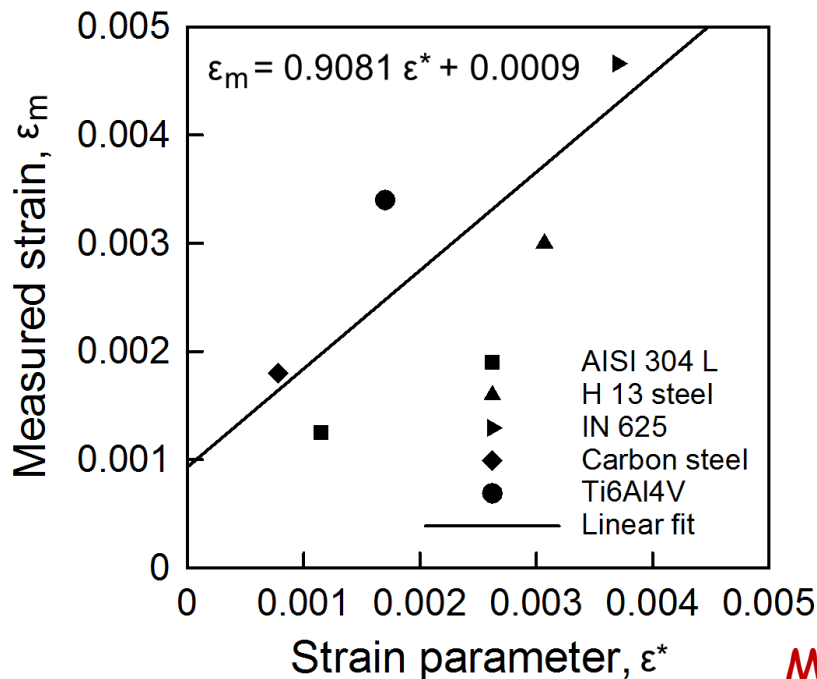


# Measure of thermal distortion: Strain parameter

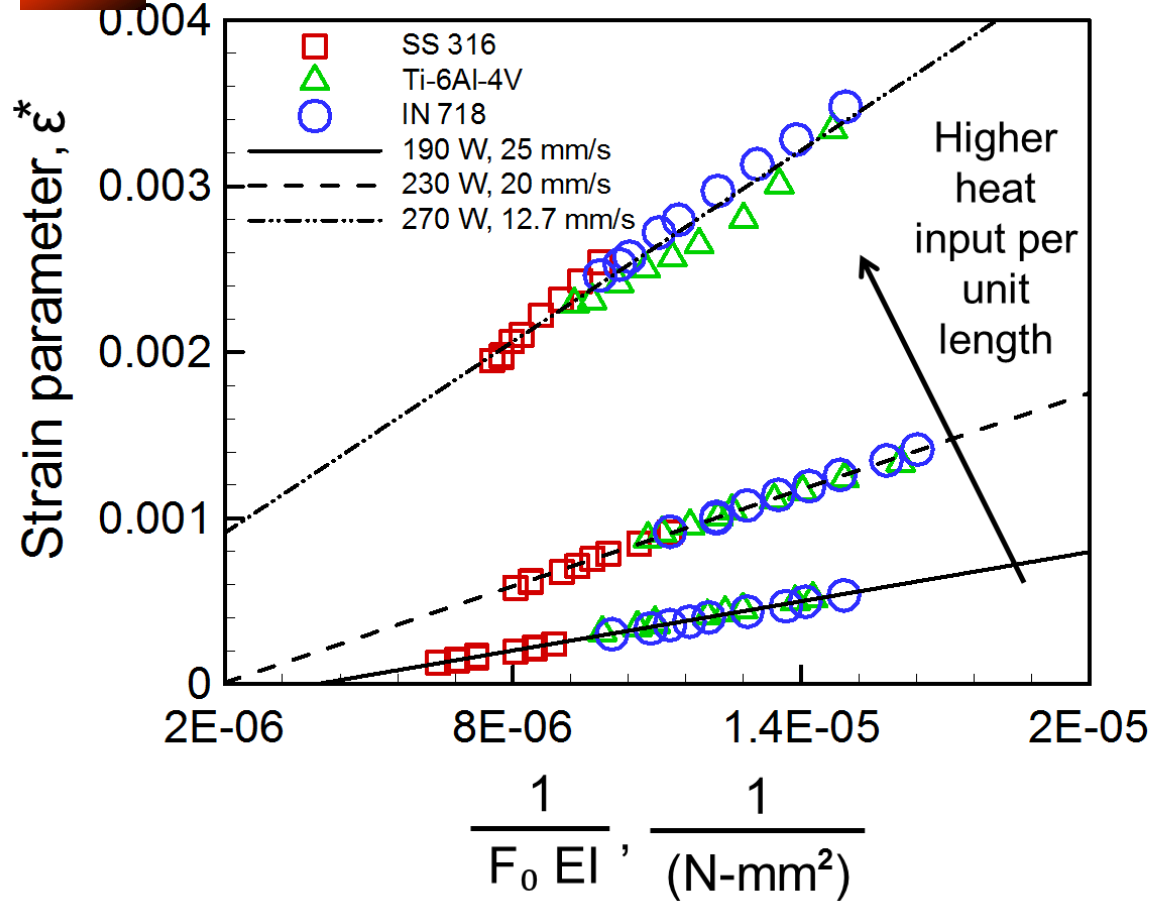
$$\varepsilon^* = \frac{\beta \Delta T}{EI} \frac{t}{F \sqrt{\rho}} H^{3/2}$$

- $\varepsilon^*$  is obtained by dimensional analysis
- $\varepsilon^*$  provides insight to thermal strain and distortion in AM
- $\varepsilon^*$  does not consider any plastic deformation

Variables	Symbols
Thermal expansion coefficient	$\beta$
Temperature difference	$\Delta T$
Fourier number	$F$
Heat input per unit length	$H$
Total time	$t$
Flexural rigidity of substrate	$EI$
Density	$\rho$



# Thermal strain vs. Fourier number



Fourier number ( $F_0$ ) =

Heat dissipation rate

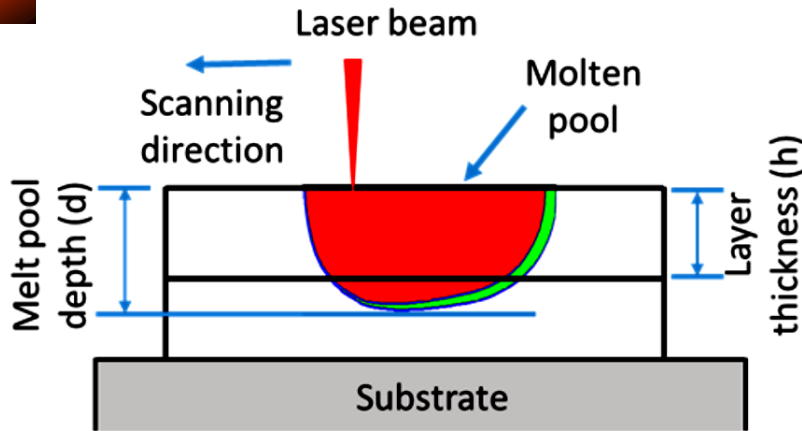
Heat storage rate

$EI$  = Flexural rigidity of the substrate

$$\epsilon^* = \frac{\beta \Delta T}{EI} \frac{t}{F \sqrt{\rho}} H^{3/2}$$

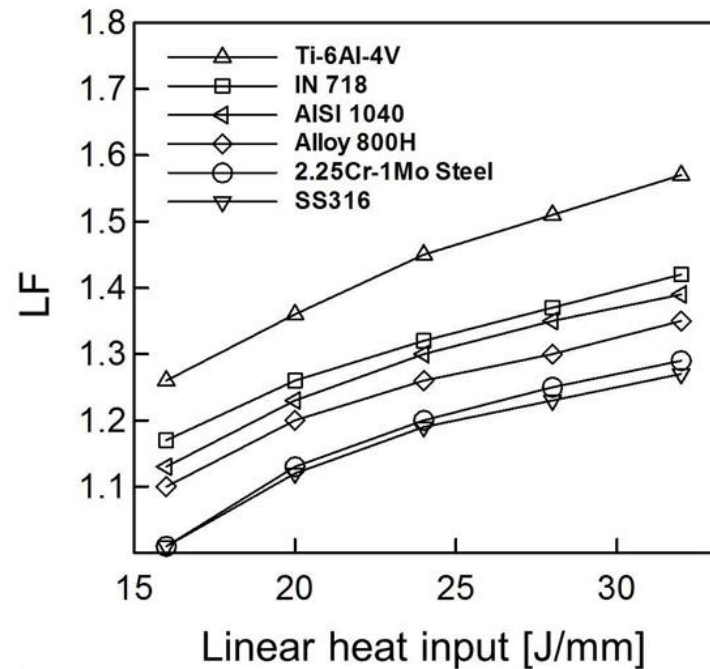
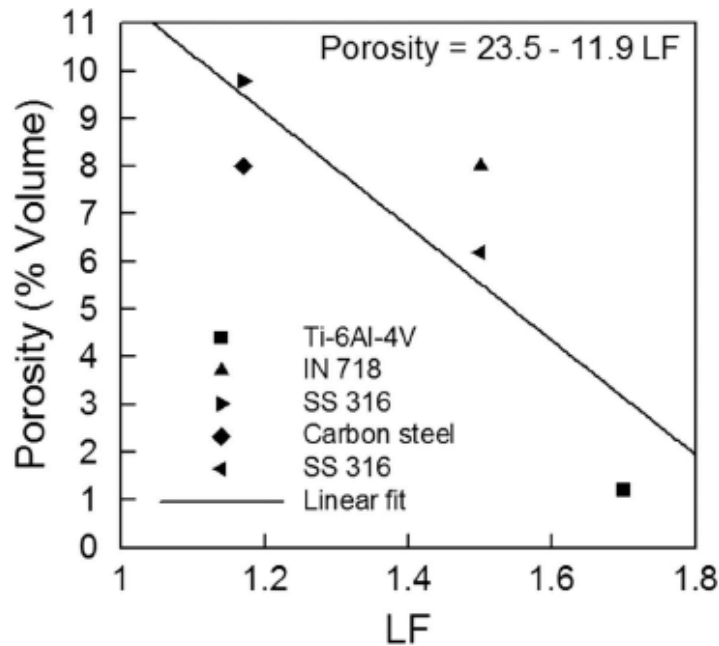
- Low  $F_0 \Rightarrow$  High heat storage  $\Rightarrow$  High thermal strain and distortion
- Low  $EI \Rightarrow$  Less rigid substrate  $\Rightarrow$  High thermal strain and distortion

# Lack of fusion defect



Lack of fusion index (LF) =

$$\frac{\text{Pool depth (d)}}{\text{Layer thickness (h)}}$$



# Summary and conclusions



- ❖ A 3D transient heat transfer and fluid flow model is used to calculate the important metallurgical variables.
- ❖ Lower heat input results in faster cooling, smaller grain size and high hardness.
- ❖ Lower layer thickness and heat input selected by trading off both distortion and residual stresses are useful to fabricate dimensionally accurate part with minimum residual stress.
- ❖ High Fourier no. (high heat dissipation and low heat storage) can effectively reduce thermal distortion.
- ❖ Lager molten pool at higher heat input ensures proper fusional bonding between layers.